Abstract

Carrier, method for coating a carrier, and method for the simultaneous double-side material-removing machining of semiconductor wafers

The invention relates to a carrier, suitable for receiving one or more semiconductor wafers for the machining thereof in lapping, grinding or polishing machines, comprising a core composed of a first material, which has a high stiffness, said core being completely or partly coated with a second material, and also at least one cutout for receiving a semiconductor wafer, wherein the second material is a thermoset polyurethane elastomer having a hardness of 20-90 according to Shore A. The invention additionally relates to a method for coating carriers and a method for the simultaneous double-side material-removing machining of a plurality of semiconductor wafers using such carriers.

Fig. 1